

Application No.: 09/661,281

**AMENDMENTS TO THE CLAIMS:**

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*Please amend the claims as follows:*

1-32. (Cancelled)

33. (Currently amended) A circuit substrate comprising:

a substrate including a first surface and a second surface opposite to the first surface;

a first conductor pattern formed on the first surface; and

a second conductor pattern formed on the second surface,

wherein ~~if the circuit substrate is mounted on a second substrate, the second surface is the surface mounted to the second substrate, and the first surface is adapted for mounting a device smaller than the substrate,~~

the second surface is adapted for mounting to a second substrate, and

the second surface has larger surface roughness than the first surface.

34. (Previously presented) A circuit substrate according to claim 33, further comprising an external terminal formed on the second conductor pattern.

35. (Cancelled)

36. (Previously presented) A circuit substrate according to claim 34, wherein the external terminal is a ball-shaped solder.

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37. (Previously presented) A circuit substrate according to claim 33, further comprising a through hole in the substrate connecting the first and second surface.

38. (Previously presented) A circuit substrate according to claim 37, further comprising an electrode filled in the through hole.

39. (Previously presented) A circuit substrate according to claim 37, further comprising an electrode formed along the through hole.

40. (Previously presented) A circuit substrate according to claim 38, wherein the external terminal is connected directly underneath the electrode.

41. (Previously presented) A circuit substrate according to claim 39, further comprising a solder filled in the through hole.

42. (Previously presented) A circuit substrate according to claim 41, wherein the solder has a higher melting point than the external terminal.

43. (Previously presented) A circuit substrate according to claim 33, further comprising a dielectric layer formed on at least a portion of the first and/or second conductor patterns; and a third conductor pattern formed on the dielectric layer.

44-52. (Cancelled)

53. (New) A circuit substrate according to claim 33, further comprising an insulating layer covering the second conductor pattern on the second surface.

54. (New) A circuit substrate according to claim 33, further comprising an electrode filled in a through hole of the substrate,

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wherein the electrode connects the first conductor pattern with the second conductor pattern, and

the second conductor pattern covers the electrode on the second surface and includes the same metal as the electrode.